

CLAIMS

1. A method for manufacturing a micromachine including an oscillator, comprising:

5 a step of forming a sacrifice layer around a movable portion of the oscillator;

a step of covering the sacrifice layer with an overcoat film, followed by the formation of a penetrating hole reaching the sacrifice layer in the overcoat layer;

10 a step of performing sacrifice-layer etching for removing the sacrifice layer using the penetrating hole in order to form a space around the movable portion; and

15 a step of performing a film-formation treatment at a reduced pressure following the sacrifice-layer etching so as to seal the penetrating hole.

2. The method for manufacturing a micromachine, according to Claim 1, wherein the method is applied to a micromachine having means for driving oscillation in the oscillator.

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3. The method for manufacturing a micromachine, according to Claim 2, wherein static electricity is used as the means for driving oscillation.

25 4. The method for manufacturing a micromachine, according

to Claim 2, wherein piezoelectricity is used as the means for driving oscillation.

5. The method for manufacturing a micromachine, according  
5 to Claim 1, wherein the film-formation treatment at a reduced pressure is a film-formation treatment by sputtering.